

ATROX® 800HT2VX

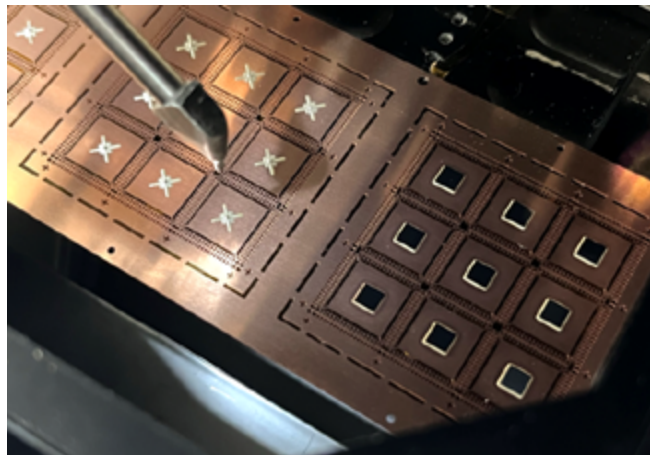
PFAS-Free Hybrid Silver Sintered Die Attach Paste

ATROX 800HT2VX is a dispensable thermosetting die attach paste with a very high thermal conductivity for high-power semiconductor packages using metallized dies.

It has low resin-bleed out and low condensable organics which will ensure excellent package reliability.

KEY FEATURES

- Highly electrically and thermally conductive
- High throughput and dispensable die attach
- Excellent adhesion to most lead-frame and substrate surfaces
- Proven MSL and reliability performance
- Uses sub-micron sized powder fillers (<1µm)
- High Viscosity/Thixotropic Index enables tight controlled epoxy spread, close die-to-die/die-paddle distance
- Prevent die attach creep up onto thin dies (less than 4mils)
- Sub-micron sized particles fillers enables low BLT process settings without voiding



TYPICAL PROPERTIES

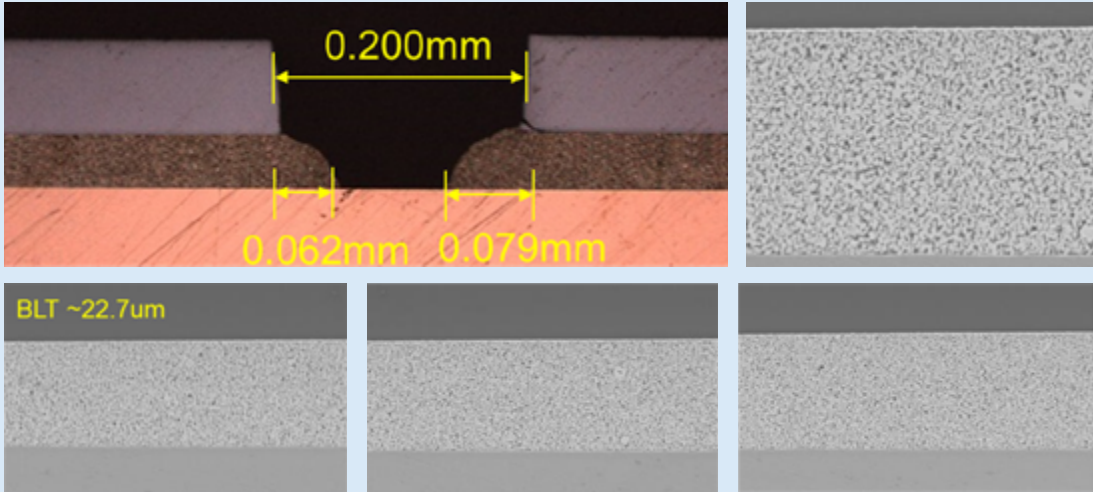
PROPERTIES	800HT2VX
Chemical Type	Thermosetting
Appearance	Grey
Viscosity at 25 °C at 5RPM	58,000 CPs
Thixotropic Index	5.0
Pot Life @ 23°C (elapsed time for 25% increase in viscosity)	> 24 hours
Filler particle size (Average)	< 1 micron
Modulus @25C @260C	11.7 GPa 2.7 GPa
Thermal Conductivity (W/mK)	> 175 W/mK
Vol. Resistivity (ohm.cm)	0.000014
Shelf Life @-40(°C/ °F)	6 months
Cure Profile	30min +150°C/30min + 20min + 200°C/2hr

ATROX® 800HT2VX

PFAS-Free Hybrid Silver Sintered Die Attach Paste

MATERIAL PERFORMANCE / DATA

High Viscosity/
Thixotropic
Index enables
defect-free
assembly of
tight tolerance
spacing
between dies.



ATROX® 800HT2VX prevents die top contamination in thin die applications due to its high viscosity/thixo which prevents the die attach from creeping onto die top.
It has controlled epoxy spread, so two dies can be placed side by side within a tight <200µm spacing.

Sub-micron filler
enables defect-
free processing
and equal
reliability with
low BLT settings.

	1_Cu LF 24um	2_Ag LF 24um	3_PPF LF 24um	4_Cu LF 13um	5_Ag LF 13um	6_PPF LF 13um
T0hr						
TC1000						
	0/18 units possible delam	0/18 units possible delam	0/18 units possible delam	0/18 units possible delam	0/18 units possible delam	0/17 units possible delam

Sub-micron fillers in ATROX® 800HT2VX enable lower BLT process settings, and still achieve comparably good workability and reliability results as with standard 1mil thickness.

